©	Material Composit Copyright 2005. IPC, J International and Pan-An	Bannockb	urn, Illinois. A	ll rights reserved untions.	inder both	This docume level parts, t	ent is a decla he declaratio	ration of the	e substances sses all lowe	within the	e manufacture aterials for wh	er listed ite hich the m	em. Note anufactu	e: if the ite rer has er	em is an asse ngineering res	mbly with lower ponsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mfg Information					
Supplier Information	on															
Company name*			Company unique ID			Unique ID Authority					Response Date*					
onsemi										2024-05-16						
Contact Name	Title - Contact				Phone - Contact*					Email - Contact*						
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com					
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester Ite	Requester Item Number Mfr Iter		n Number Mfr Item Name			Effec		ate Versio	on I	Manufacturing Site		v	Veight*	U	JOM	Unit Type
	CAV2501		10VE-GT3	1KB SPI SER CMOS EEPROM			2024-05-16		I	PH1		7	7.46	n	ıg	Each
Manufacturing Pro	occess Information	L					·									
Terminal Plating / Grid Array Material			erminal Base A	rminal Base Alloy J-STD-0		L Rating	Peak P	Process Body Temperature		are Max Time at Peak Tempe		Temperatu	perature Number of Reflow Cycles		3	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		C	30 seco		second	econds 3			
Comments																
evel 1 - maximum time	at peak temperature d	luring sol	dering is 10-3	0 seconds												
For more information re	egarding material com	position j	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl hthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.65	mg	Supplier	Silicon (Si)	7440-21-3		2.65	mg
Die Attach	0.21	mg		Epoxy resin	proprietary data		0.021	mg
			Supplier	Silver (Ag)	7440-22-4		0.168	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.021	mg
Lead Frame	27.35	mg	Supplier	Zinc (Zn)	7440-66-6		0.0274	mg
			Supplier	Iron (Fe)	7439-89-6		0.6291	mg
			Supplier	Copper (Cu)	7440-50-8		26.6663	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0274	mg
Mold Compound-Black	46.76	mg		Epoxy resin	proprietary data		2.338	mg
			Supplier	Phenolic Resin	Proprietary Data		2.338	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.9352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2338	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.915	mg
Plating	0.34	mg	Supplier	Palladium (Pd)	7440-05-3		0.0211	mg
			В	Nickel (Ni)	7440-02-0		0.3152	mg
			Supplier	Gold (Au)	7440-57-5		0.0036	mg
Wire Bond - Au	0.15	mg	Supplier	Gold (Au)	7440-57-5		0.15	mg